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### **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **LISTING OF CLAIMS:**

Claims 1-12 (canceled).

Claim 13 (currently amended): An integrated circuit package comprising:  
a substrate having a plurality of conductive traces;  
a plurality of balls disposed on a first surface of said substrate;  
a semiconductor die mounted to said substrate such that bumps of said semiconductor die are electrically connected to said plurality of conductive traces of said substrate;

an overmold material encapsulating said semiconductor die and said balls on said substrate such that portions of said balls that are disposed farthest from said substrate are exposed at an exterior of said integrated circuit package; and

a ball grid array disposed on a second surface of said substrate and in electrical connection with said conductive traces.

Claim 14 (canceled).

Claim 15 (currently amended): The integrated circuit package according to claim 13, wherein said plurality of balls is attached to respective solder ball pads on said first surface of said substrate.

Claim 16 (original): The integrated circuit package according to claim 13, wherein said bumps of said semiconductor die are electrically connected to said



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conductive traces by wire bonds.

Claim 17 (original): The integrated circuit package according to claim 13, wherein said semiconductor die is fixed to said first surface of said substrate.

Claim 18 (currently amended): The integrated circuit package according to claim 13, further comprising a metal strip, wherein a first surface of said metal strip is laminated to a said second surface of said substrate, wherein bumps of said ball grid array are mounted to said plurality of balls.

Claim 19 (currently amended): The integrated circuit package according to claim 18, wherein said semiconductor die is mounted to said first surface of said metal strip in a cavity in said substrate such that said semiconductor die is mounted to said substrate via said metal strip.

Claim 20 (original): The integrated circuit package according to claim 13, wherein said plurality of balls circumscribe said semiconductor die.

Claim 21 (currently amended): The integrated circuit package according to claim 13, wherein said plurality of balls is electrically connected to said conductive traces of said substrate.

Claim 22 (original): The integrated circuit package according to claim 13, wherein said balls are deformed.

Claim 23 (original): The integrated circuit package according to claim 13, further comprising a die adapter mounted on said semiconductor die and encapsulated in said overmold material.



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Claim 24 (canceled).

Claim 25 (original): The integrated circuit package according to claim 13, wherein said plurality of balls is comprised of a plurality of solder balls.

Claim 26 (new): An integrated circuit package comprising:  
a substrate having a plurality of conductive traces;  
a plurality of balls disposed on a first surface of said substrate;  
a semiconductor die mounted to said substrate such that bumps of said semiconductor die are electrically connected to said plurality of conductive traces of said substrate;

an overmold material encapsulating said semiconductor die and said balls on said substrate such that portions of said balls that are disposed farthest from said substrate are exposed; and

a ball grid array disposed on said portions of said balls that are disposed farthest from the substrate that are exposed, the ball grid array being in electrical connection with said conductive traces through said plurality of balls.